



# Live Events

**Time:**  
9:00 a.m. to 3:00 p.m.

## ANSYS Solutions for the Electronics Industry

**Location:**

[April 4: San Jose, CA](#)

[April 11: Washington, DC area](#)

[April 18: Los Angeles, CA](#)

[April 25: Minneapolis, MN](#)

[May 2: Raleigh, NC](#)

[May 9: Toronto, ON, Canada](#)

ANSYS, Inc. provides the electronics industry with a comprehensive suite of simulation tools covering structural, thermal, CFD, electromagnetics and acoustics simulation. This free seminar will introduce analysts and designers to the depth of capabilities and the breadth of industry and physics applications in the product portfolio from ANSYS.

### Agenda

8:30 a.m. – 9:00 a.m.	Registration
9:00 a.m. – 9:30 a.m.	Welcome/Introduction of products and ANSYS® Workbench™
9:30 a.m. – 10:30 a.m.	Thermal management <ul style="list-style-type: none"> <li>• Chip, board and system level analysis with ANSYS® Icepak® and ANSYS® Iceboard® software</li> <li>• Advanced cooling and acoustics modeling with FLUENT® and ANSYS® CFX® software</li> </ul>

**Who should attend:**

- Users of ANSYS software who are interested in new capabilities and physics
- Others interested in learning about product offerings from ANSYS

10:40 a.m. – 11:40 a.m.	Structural and mechanical modeling <ul style="list-style-type: none"><li>• Thermal–mechanical stress and package reliability</li><li>• Drop test and vibration analysis</li></ul>
11:40 a.m. – 12:30 p.m.	Electromagnetic modeling <ul style="list-style-type: none"><li>• Parasitic extraction</li></ul>
12:30 p.m. – 1:30 p.m.	Lunch
1:30 p.m. – 2:30 p.m.	Multiphysics simulation <ul style="list-style-type: none"><li>• Piezoelectric and piezoresistivity</li><li>• Thermal–structural–electric coupling</li></ul>
2:30 p.m. – 3:00 p.m.	Product roadmap and close

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